

# CPD76X-1N5817 Schottky Rectifier Die 1.0 Amp, 20 Volt

The CPD76X-1N5817 is a silicon 1.0 Amp, 20 Volt Schottky rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.

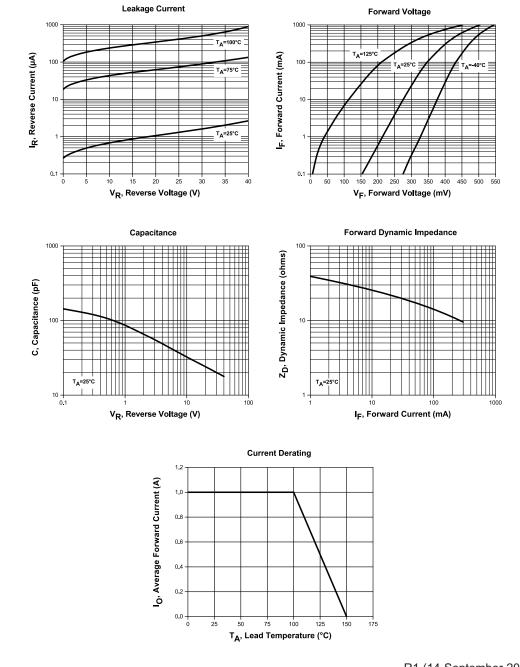
	MECHANICA	L SPECIFICAT	IONS:	
ANODE	Die Size		32 x 32 MILS	
	Die Thicknes	s	5.9 MILS	
	Anode Bond	ing Pad Size	27 x 27 MILS	
	Top Side Me	talization	AI – 20,000Å	
	Back Side M	etalization	Au – 9,000Å	
	Scribe Alley	Width	2.36 MILS	
	Wafer Diame	eter	5 INCHES	
	Gross Die Pe	er Wafer	16,276	
BACKSIDE CATHODE R	 			
MAXIMUM RATINGS: (T <sub>A</sub> =25°	C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage		VRRM	20	V
DC Blocking Voltage		VR	20	V
RMS Reverse Voltage		V <sub>R(RMS)</sub>	14	V
Average Forward Current (T <sub>A</sub> =100°C)		IO	1.0	А
Peak Forward Surge Current, tp=8.3ms		IFSM	25	А
Operating and Storage Junction Temperature		T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
ELECTRICAL CHARACTERIS	<b>ΓΙCS</b> : (Τ <sub>Δ</sub> =25°C ι	unless otherwise	e)	
SYMBOL TEST CONDITIONS		MIN	MAX	UNITS
I <sub>R</sub> V <sub>R</sub> =20V			1.0	mA
V <sub>F</sub> I <sub>F</sub> =0.1A	I <sub>F</sub> =0.1A		320	mV
V <sub>F</sub> I <sub>F</sub> =1.0A	I <sub>F</sub> =1.0A		450	mV
	I <sub>F</sub> =3.1A		750	mV
V <sub>F</sub> I <sub>F</sub> =3.1A				

#### MECHANICAL SPECIFICATIONS:

# **CPD76X-1N5817** Typical Electrical Characteristics



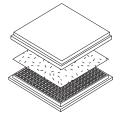
www.centralsemi.com



R1 (14-September 2016)

## BARE DIE PACKING OPTIONS



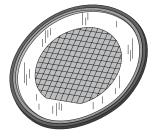


## BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

## **UNSAWN WAFER**

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



## SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

www.centralsemi.com

## **OUTSTANDING SUPPORT AND SUPERIOR SERVICES**

#### **PRODUCT SUPPORT**

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

#### **DESIGNER SUPPORT/SERVICES**

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

Special wafer diffusions

· Custom product packing

- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

## **REQUESTING PRODUCT PLATING**

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

### CONTACT US

## **Corporate Headquarters & Customer Support Team**

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA Main Tel: (631) 435-1110 Main Fax: (631) 435-1824 Support Team Fax: (631) 435-3388 www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors: www.centralsemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: <u>www.centralsemi.com/terms</u>

